

Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) An electronic parts mount method for taking out electronic parts in wafer shape and transporting and mounting the electronic parts to and on a board ~~by a~~ using transfer head including a plurality of suction nozzles, the method comprising the steps of:

~~image-picking-up-for~~ picking up an image of the electronic parts in wafer shape by advancing an image pickup means to above a wafer hold section for holding the electronic parts, wherein the image pick up means is disposed in a manner that the image pick up means can advance to and retreat from the wafer hold section;

~~position-detecting-for~~ detecting positions of the electronic parts based on the image of the electronic parts ~~image data obtained by the step of image-picking-up;~~

~~parts-taking-out-for~~ controlling the a head move means for moving the transfer head based on the detected positions, ~~a result of the step of position-detecting,~~ and taking out the electronic parts in order from the wafer hold section ~~by~~ using the transfer head; and

~~parts-mounting-for~~ moving the transfer head to above the board that is positioned by a board

positioning section, and mounting the electronic parts on the board;

wherein the step steps of parts mounting the electronic parts is performed concurrently with the step of and image picking up an image of ~~for~~ the electronic parts to be next taken out ~~are performed concurrently.~~

2. (currently amended) The electronic parts mount method according to claim 1, wherein, in the step of picking up the image ~~picking up~~, the image picked up by the pickup means, when the image pick up means is advanced to above the wafer hold section, ~~picks up an image is~~ of a plurality of electronic parts ~~when the image pick up means is advanced to above the wafer hold section.~~

3. (original) The electronic parts mount method according to claim 2, wherein, the plurality of electronic parts whose image is picked up by the image pickup means are electronic parts to be next taken out by the transfer head.

4. (currently amended) The electronic parts mount method according to claim 1, wherein, in the step of picking up the image ~~picking up~~, the image pickup means retreats to the front side of the side of a wafer stock section placed adjacent to the wafer hold section after picking up the image of the electronic parts, and the transfer head is moved to above the wafer hold section.

5. (new) An electronic parts mount method for taking out electronic parts in wafer shape and transporting and

mounting the electronic parts to and on a board using transfer head including a plurality of suction nozzles, the method comprising the steps of:

picking up an image of the electronic parts in wafer shape by advancing an image pickup means to above a wafer hold section for holding the electronic parts, wherein the image pick up means is disposed in a manner that the image pick up means can advance to and retreat from the wafer hold section;

detecting positions of the electronic parts based on the image of the electronic parts;

controlling a head move means for moving the transfer head based on the detected positions, and taking out the electronic parts in order from the wafer hold section using the transfer head; and

moving the transfer head to above the board that is positioned by a board positioning section, and mounting the electronic parts on the board;

wherein the step of mounting the electronic parts is performed concurrently with the step of picking up an image of the electronic parts to be next taken out, and

wherein, in the step of picking up the image, the image pickup means retreats to the front side of the side of a wafer stock section placed adjacent to the wafer hold section after picking up the image of the electronic parts, and the transfer head is moved to above the wafer hold section.